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Client Matter No. 81848.0016.002
Express Mail No.: EV330612472US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No. 09/991,196 Application of: Chih-Chien Liu, Ta-Shan Tseng, W. B. Shieh, J. Y. Wu, Water Lur and Shih-Wei Sun Filed: November 20, 2001 Art Unit: 1711 Examiner: Rabon A. Sergeant Attorney Docket No. UMC-96-279 CON2 JIA-462C1 For: HIGH DENSITY PLASMA CHEMICAL VAPOR DEPOSITION PROCESS	Confirmation No.: 3908 Customer No.: 25235
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AMENDMENT

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the office communication mailed March 17, 2005, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 8 of this paper.

A **Terminal Disclaimer** is attached following page 10 of this paper.

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